

ASIC	Application Specific Integrated Circuit
BGA	Ball Grid Array
BPO	Bond Pad Opening
BPP	Bond Pad Pitch
COB	Chip on Board
CSP	Chip Scale Package
DIP	Dual In-line Package
EFO	Electronic Flame Off
FAB	Free Air Ball
HDI	High Density Interconnects
I/O	Input/Output
IC	Integrated Circuit
LED	Light Emitting Diode
LTCC	Low-Temperature Co-fired Ceramics
mBGA	Micro Ball Grid Array
MBGA	Metal Ball Grid Array
MCM	Multi Chip Module
MCP	Multi Chip Packaging
MEMS	Micro Electro Mechanical Systems
MMS	Micro Module System(s)
PCB	Printed Circuit Board
PGA	Pin Grid Array
PLCC	Plastic Leaded Chip Carrier
QFN	Quad Flat Non-leaded
QFP	Quad Flat Pack
SEM	Scanning Electron Microscope
SIP	Single In-line Package
SMT	Surface Mount Technology
SOC	System on Chip
SOIC	Small Outline Integrated Circuit
SOJ	Small Outline J-bend
SOP	Small Outline Package
TSOP	Thin Small Outline Package
VLSI	Very Large Scale Integrated Circuit